

### Amendments to the Claims

Listing of Claims:

Claims 1 - 13 (canceled).

Claim 14 (new). An electronic module, comprising:

at least one circuit carrier having a first side, a second side opposite said first side, and an electroconductive material coating both said first and second sides;

a first group of electronic components for forming a user interface applied and connected onto said first side of said circuit carrier; and

a second group of electronic components for forming a computing and control module applied and connected onto said second side of said circuit carrier.

Claim 15 (new). The electronic module according to claim 14, wherein said circuit carrier is free from through-connection points, including silver through hole through-connection points.

Claim 16 (new). The electronic module according to claim 14, wherein said circuit carrier includes at least one signal transmission device for two-way transmission of control

signals between said first group of electronic components on said first side of said circuit carrier and said second group of electronic components on said second side of said circuit carrier and/or for supplying said first side with electrical power via said second side or conversely.

Claim 17 (new). The electronic module according to claim 16, wherein:

said circuit carrier has an edge region and plug-in regions on both said first and second sides;

said signal transmission device has at least one plug-in element plugging into said edge region of said circuit carrier via opposite said plug-in regions formed on said first and said second side of said circuit carrier and conjugate with one another.

Claim 18 (new). The electronic module according to claim 16, wherein:

said first side of said circuit carrier has a first contact region;

said second side of said circuit carrier has a second contact region;

said signal transmission device has at least one conductor element electrically connecting said first contact region to said second contact region.

Claim 19 (new). The electronic module according to claim 16, wherein:

said circuit carrier has a through-hole formed therein;

said first side of said circuit carrier has a first contact region;

said second side of said circuit carrier has a second contact region;

said signal transmission device has at least one through-connection element running through said through-hole in said circuit carrier and electrically connects said first contact region to said second contact region.

Claim 20 (new). The electronic module according to claim 19, wherein said through-connection element is a plug-in element formed of sheet metal, said plug-in element having a spring section, a plane contact surface and a pin region spring-connected to said contact surface by said spring section, said contact surface abuts flush against at least one of said first and second contact regions of said circuit carrier, said pin region runs through said through-hole when said

plug-in element is inserted in said through-hole as said through-connection element.

Claim 21 (new). The electronic module according to claim 14, wherein:

said first side has a first SMD region;

said second side has a second SMD region and a THD region, said THD region is different from said second SMD region, said second SMD region is a region corresponding to and opposite to said first SMD region of said first side;

said first group of electronic components are mounted on said first SMD region by SMD technology; and

said second group of electronic components are mounted on said second SMD region by SMD technology and also in said THD region by THD technology.

Claim 22 (new). The electronic module according to claim 14, wherein:

said first side has a first SMD region and a THD region being different from said first SMD region;

said second side has a second SMD region, said second SMD region is a region corresponding to and opposite to said first SMD region of said first side;

said first group of electronic components are mounted on said first SMD region by SMD technology and also mounted on said THD region by THD technology; and

said second group of electronic components are mounted on said second SMD region of said second side by SMD technology.

Claim 23 (new). The electronic module according to claim 18, wherein said conductor element is a cable jumper.

Claim 24 (new). A method for producing an electronic module, which comprises the steps of:

providing a circuit carrier;

loading a first side of the circuit carrier with a first group of electronic components for forming a user interface of the electronic module;

loading a second side of the circuit carrier with a second group of electronic components for forming a computing and control module; and

setting up signal transmission and/or power supply connections between the first side and the second side.

Claim 25 (new). The method according to claim 24, wherein the setting up step further comprises:

forming plug-in regions extending on an edge region in an opposed and mutually conjugate manner on the first side and the second side of the circuit carrier; and

plugging a plug-in element onto the oppositely constructed and mutually conjugate plug-in regions.

Claim 26 (new). The method according to claim 24, wherein the setting up step further comprises:

forming at least one first contact region on the first side of the circuit carrier and at least one second contact region on the second side of the circuit carrier; and

connecting the at least one first contact region to the at least one second contact region with a conductor element.

Claim 27 (new). The method according to claim 24, wherein the setting up step further comprises:

forming at least one through hole in the circuit carrier;

forming at least one contact region on the first side of the circuit carrier and at least one second contact region on the second side of the circuit carrier; and

inserting a through-connection element into the at least one through hole to electrically connect the at least one first contact region to the at least one second contact region.